

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC098N10NS5	**Issued**	27. April 2022
MA#	MA005729467		
Package	PG-TDSON-8-51	**Weight***	100.50 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.629	0.63	0.63	6260	6260
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		136	
	non noble metal	zinc	7440-66-6	0.055	0.05		542	
	non noble metal	iron	7439-89-6	1.090	1.08		10849	
	non noble metal	copper	7440-50-8	44.271	44.07	45.21	440504	452031
wire	noble metal	gold	7440-57-5	0.036	0.04	0.04	361	361
encapsulation	organic material	carbon black	1333-86-4	0.085	0.08		850	
	plastics	epoxy resin	-	6.747	6.71		67135	
	inorganic material	silicondioxide	60676-86-0	35.871	35.69	42.48	356923	424908
leadfinish	non noble metal	tin	7440-31-5	1.264	1.26	1.26	12574	12574
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	289	289
solder	noble metal	silver	7440-22-4	0.023	0.02		228	
	non noble metal	tin	7440-31-5	0.046	0.05		457	
	non noble metal	lead	7439-92-1	0.849	0.84	0.91	8445	9130
heat sink clip	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	zinc	7440-66-6	0.011	0.01		113	
	non noble metal	iron	7439-89-6	0.228	0.23		2267	
	non noble metal	copper	7440-50-8	9.250	9.20	9.44	92039	94447
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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